



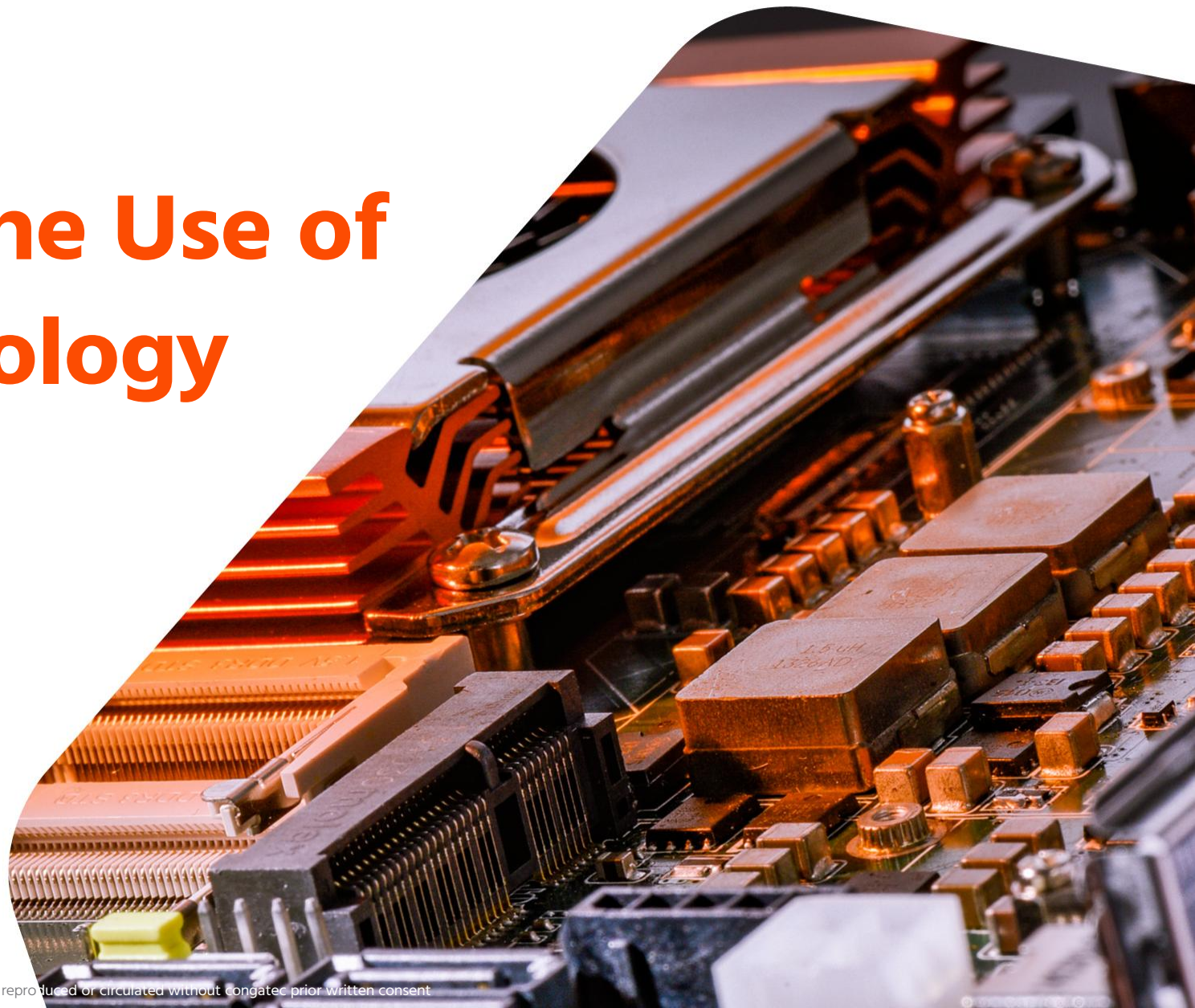
How to Simplify the Use of Embedded Technology

Embedded Conference Finland 2025

Timo Poikonen

Senior Business Development Manager EMEA

16.9.2025



Agenda

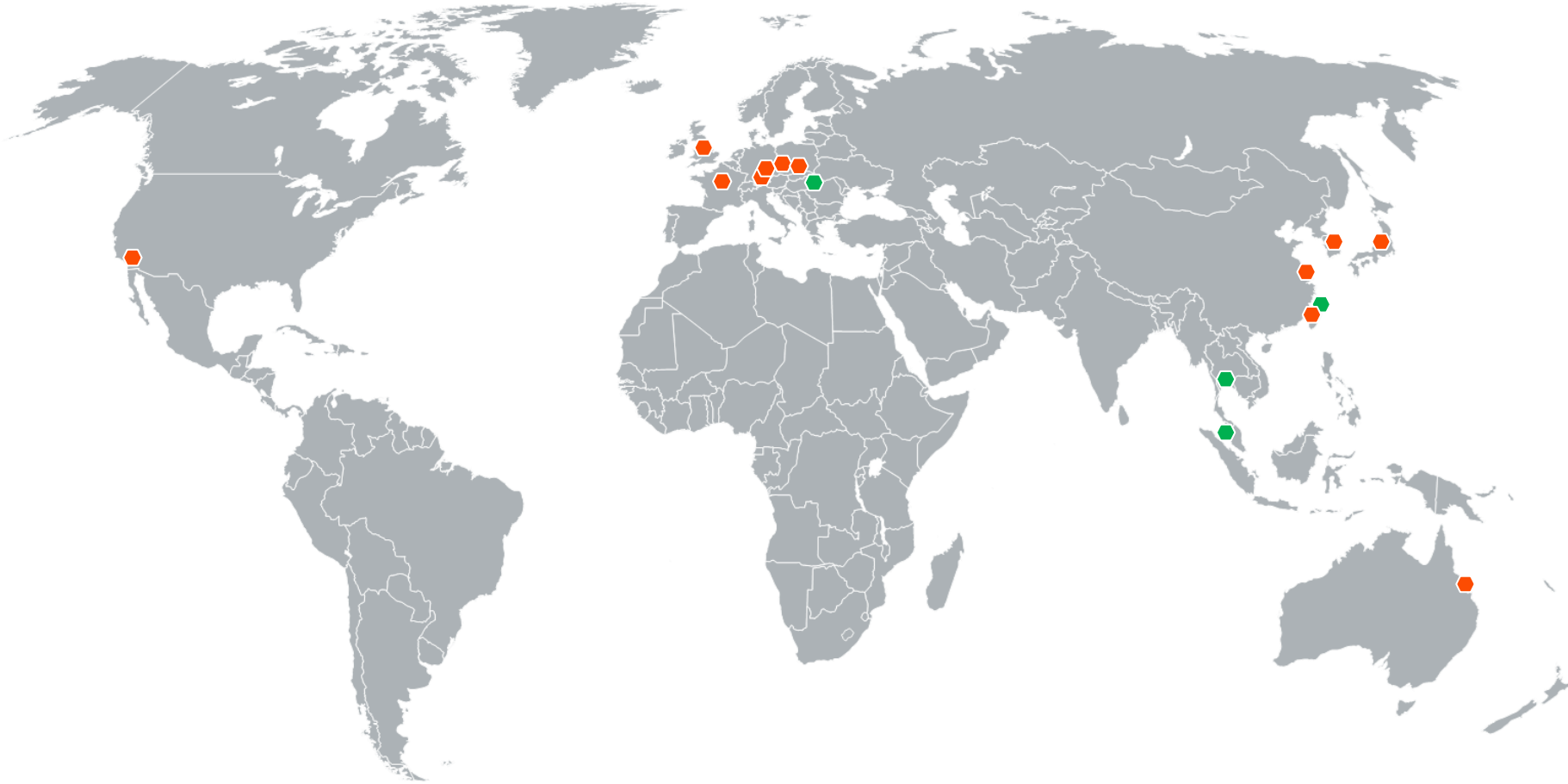
- 1. congatec @ a glance**
- 2. Innovation Leadership**
- 3. Hardware building blocks**
- 4. Software building blocks**



congatec @ a glance



Global footprint



+400

Employees worldwide
(~ 25% in R&D and tech. Support)

+10Mio

Shipped embedded solutions

+1200

Customers from various industries

Innovation leadership

Proven by customers and partners

Active Technology Leader



Active leader in setting new and innovative standards

Preferential Access Granted



Intensive technological partnership with leading global CPU providers resulting in early access to CPU roadmaps

Technological Edge



Acquired in 2018, RTS opens the door to new customers, enabling congatec to answer new application needs while also increasing margins

Congatec acquires stake in Kontron subsidiary JUMPttec

19. Juni 2025, 13:58 Uhr | [Andreas Knoll](#)

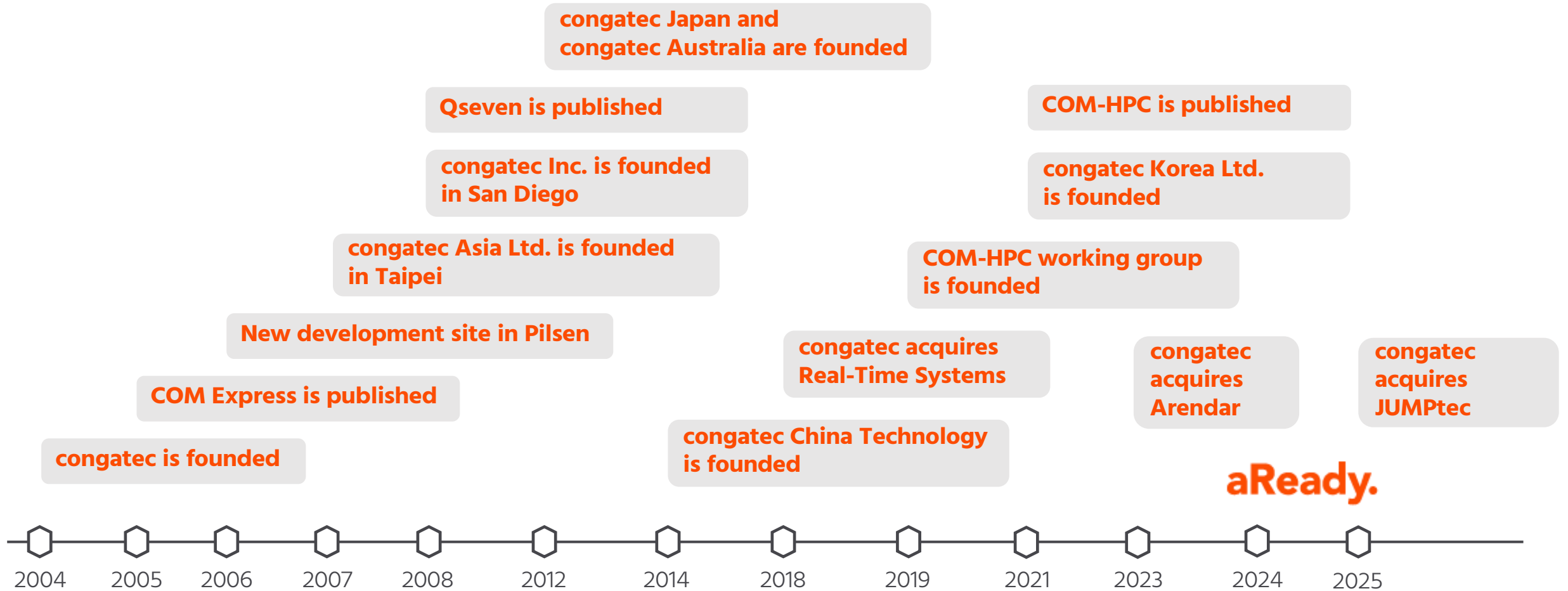


© Congatec

Konrad Garhammer, Congatec (right; left CEO Dr. Dominik Ressing): "The manufacturing cooperation with Kontron is a natural step."

Kontron and Congatec have signed a term sheet under which Congatec would acquire a majority stake in the Kontron subsidiary JUMPttec by means of a capital increase. Only a few months ago, Kontron bundled its business with plug-in Computer-on-Modules (CoMs) in the subsidiary JUMPttec GmbH.

Our milestones shaping the industry



Computer-on-Modules – Open Standards

QSeven

SMARC

COM Express

COM-HPC

COM-HPC Server

Mini | Compact |
Basic

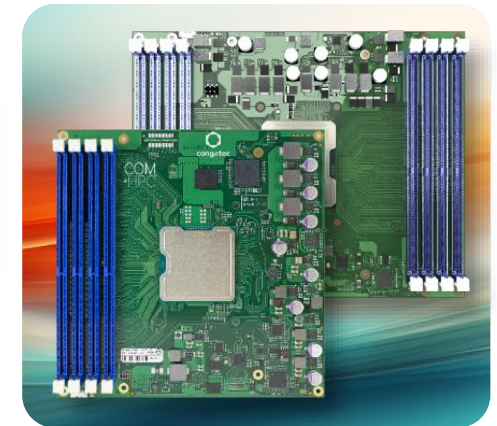
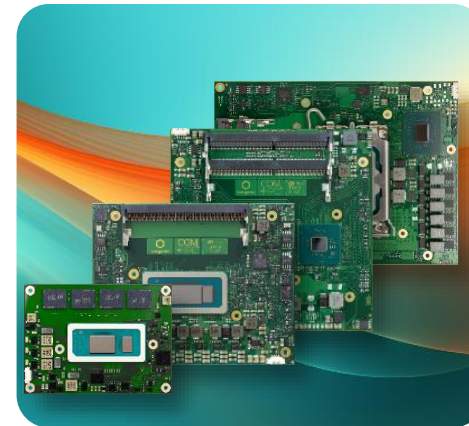
Mini
Client Size A | B | C

Server
Size D | E

Recommended for
new designs

Recommended for
new designs

Recommended for
new designs

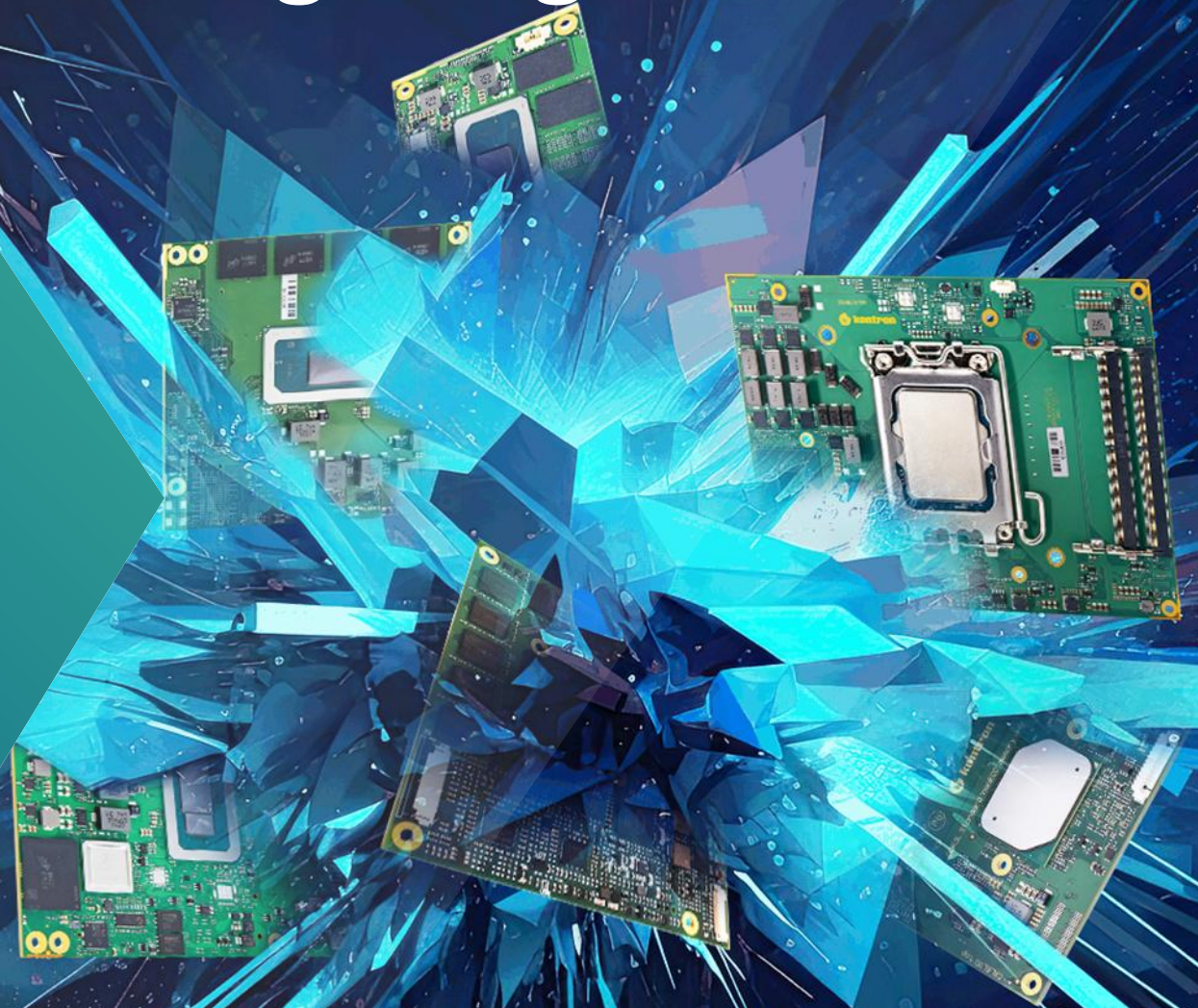


The Big Bang of Innovations

JUMPtec®

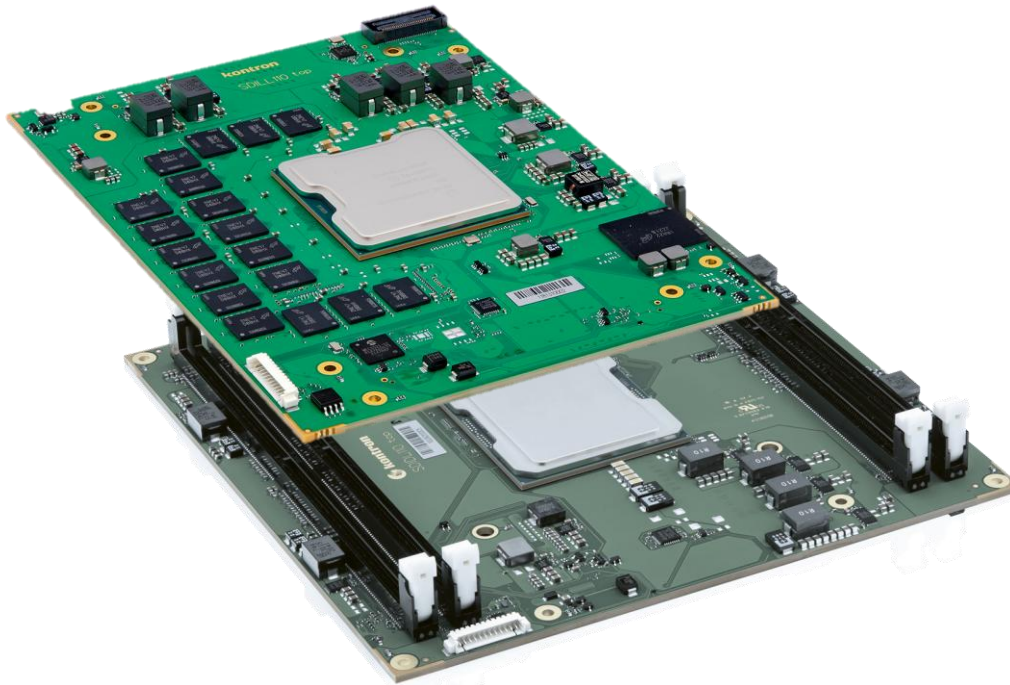
Computer-on-Modules Highlights

Deggendorf



COMh-sdIL (E2) - Feature Overview

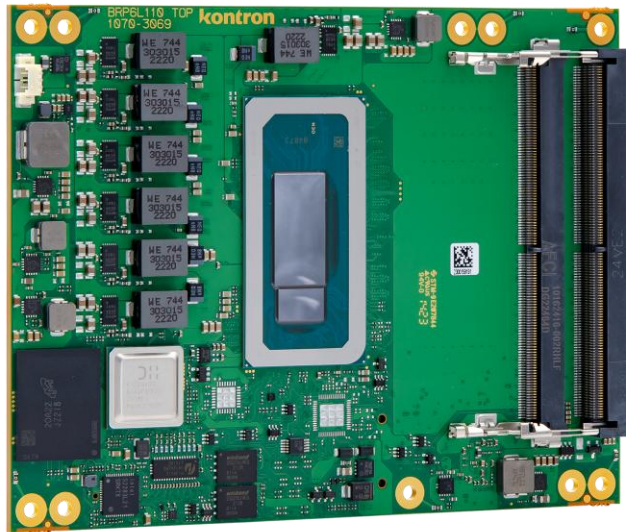
COMh-sdIL: 120 mm x 160 mm



COMh-sdID: 160 mm x 160 mm

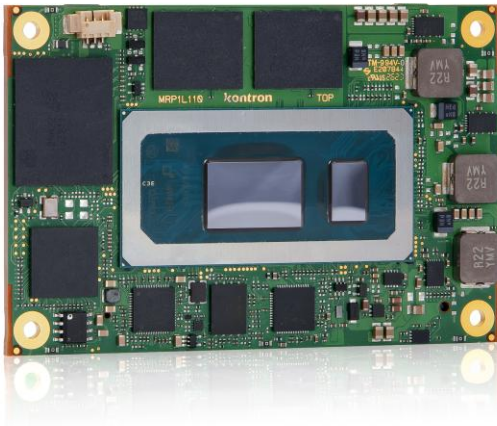
- › Intel® Xeon® D-1700 / D-1800 processor family
 - › Commercial temp. and extended temp. SKUs – 2 Cores up to 10 Cores
 - › Processor TDP up to 65W
- › Memory down for max 64 DDR4-2667 MT/s
- › LAN: 8x High-speed ports – various configurations possible + 1x 2.5GBASE-T
- › QAT (Quick Assist Technology) support – depending on CPU-SKU
- › 32x PCIe lanes: 16x PCIe Gen3 (2 x8, 4 x4, 8 x2) +
 - › 16x PCIe Gen4 (1 x16, 2 x8, 4 x4)
- › 2x SATA Gen3, 4x USB 3.0 (USB 2.0)
- › Optional onboard storage: up to 1TB NVMe
- › Industrial grade versions
- › AMI BIOS
- › Windows 10 / Server 22, Linux

COMe-bRP6 (E2) – Feature Overview



- › COM Express® basic form factor (Pin-out Type 6 compliant)
- › Based on 13th Gen Intel® Core™ technology Raptor Lake-P, supporting up to 14 cores (up to 6 P-cores and up to 8 E-cores) with Intel® performance hybrid architecture
- › Intel® Xe Graphics architecture with up to 96EUs (for dedicated SKUs)
- › Up to 64GB DDR5 non-ECC memory via 2x SODIMM sockets; IB ECC (on ind. SKUs)
- › 3x DDI + LVDS/eDP; Quad independent display support; Optional USB-C support
- › Up to 2.5Gb Ethernet with TSN support (ind. SKUs only)
- › 5x PCIe 3.0 (On request: 6x without Ethernet, up to 8x without Ethernet & SATA or alternatively 8x with additional PCIe Switch) + 2x4 PCIe 4.0 on PEG Lanes #0-7, 1x8 PCIe 4.0 on PEG Lanes #8-15 (H-series only)
- › SATA 6Gb/s & USB 3.2 Gen2 support
- › Optional NVMe SSD onboard up to 1TByte
- › E2 versions for industrial grade temp. range (-40°C up to +85°C) usage
- › OS: Windows 10 & 11 LTSC, Yocto

COMe-mRP10 (E2) – Feature Overview



- › COM Express® mini form factor (Pin-out Type 10 compliant)
- › Based on 13th Gen Intel® Core™ technology Raptor Lake-P, supporting up to 14 cores (up to 6 P-cores and up to 8 E-cores) with Intel® performance hybrid architecture
- › Intel® Xe Graphics architecture with up to 96EUs (for dedicated SKUs)
- › Up to 32GB LPDDR5(x) non-ECC memory soldered down; IBECC (on dedicated SKUs)
- › 1x DDI + LVDS/eDP; Dual independent display support
- › Up to 2.5Gb Ethernet with TSN support (ind. SKUs only)
- › 4x PCIe 3.0
- › SATA 6Gb/s & USB 3.2 Gen2 support
- › Optional NVMe SSD onboard up to 1TByte
- › E2 versions for industrial grade temp. range (-40°C up to +85°C) usage
- › OS: Windows 10 & 11 LTSC, Yocto

COMe-mAS10 (E2) – Feature Overview



- › Based on Intel® Atom® x7xxxE/x7xxxRE, supporting up to 8 cores
- › Up to 16GB LPDDR5(x) 4800MT/s non-ECC memory soldered down; IBECC
- › Graphics: Gen12 GPU, up to 32EUs on dedicated SKUs
- › Dual independent display support:
 - › 1x DDI + LVDS (optional eDP)
- › Up to 2.5Gb Ethernet with TSN support, WOL support
- › TPM support (integrated)
- › Optional eMMC onboard up to 256GB TLC
- › E2 versions for industrial grade temp. range (-40°C up to +85°C) usage
- › OS: Windows 10 & 11 LTSC, Linux based on Yocto
- › Boot Firmware: UEFI/BIOS (AMI), Slim Bootloader

conga-TC750



Drop-In Compatible Upgrade

Arrow Lake with conga-TC750 is a drop-in upgrade to conga-TC700 with upgraded performance

Next Gen Cores

New Lion Cove and Skymont P- and E-Cores with even more CPU Performance compared to Meteor Lake

Scalability

Design can scale from 15W now up to 45W



Powerful Integrated Graphics

Next gen Intel Arc Graphics with up to 128 EUs

The AI Era is here

Up to 99 TOPS total Edge AI performance enabled by XMX Systolic Array GPU design

Support for even more RAM

Utilize the full capacity of up to 128GB of total system memory with in-band ECC



COM-HPC Client Size C modules based on Intel Core 2xx series Bartlett Lake-S (preliminary)



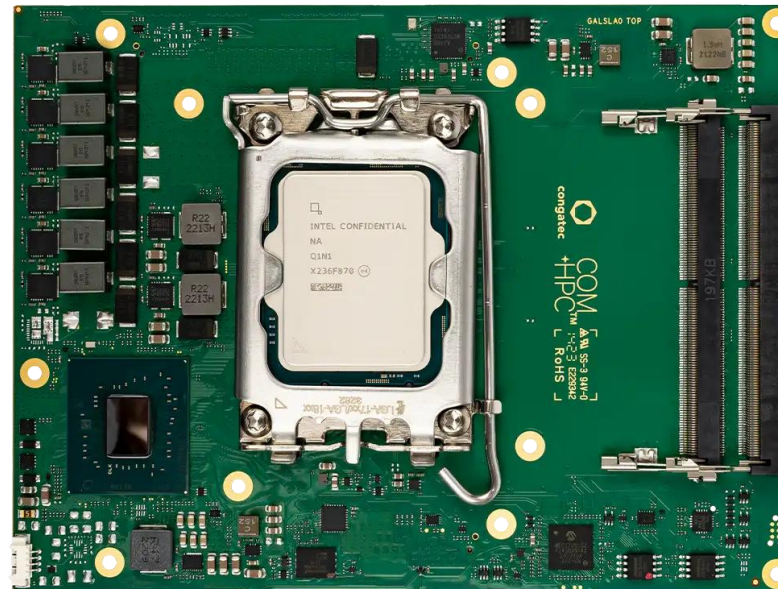
— conga-HPC/cBLS

Up to 8 P-Cores and 16 E-cores
on Intel Hybrid Architecture

Up to 12 P-Cores on Intel P-Core
Only architecture

Intel® UHD Graphics 730/770
driven by Xe Architecture

Processor Socket FCLGA 1700



4x DDR5 SO-DIMM sockets

1x PCIe Gen5 x16 |
3x PCIe Gen4 x4 |
up to 3x PCIe Gen3 x4

4x USB 3.2 Gen2x

AI Acceleration with Intel® Deep
Learning Boost



conga-TCR8



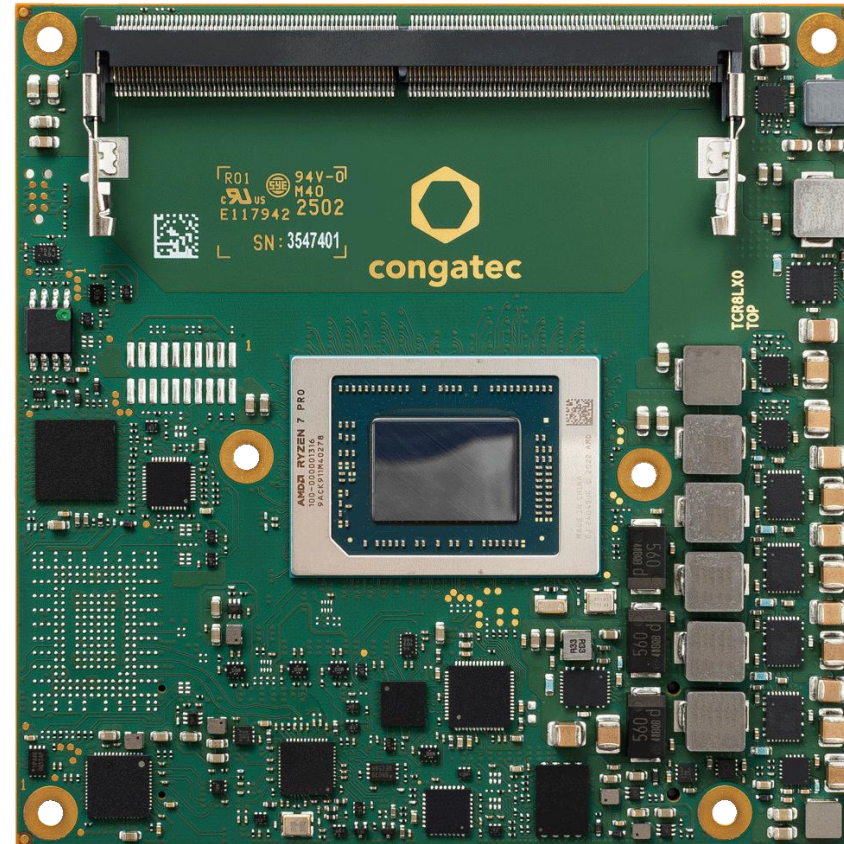
Up to 39 TOPS AI performance on a compact x86 module

High-performance architecture with **integrated CPU, GPU, and NPU**

Exceptional multipurpose computing with **up to 39 TOPS**

Highly efficient x86 computing with up to 8 Zen 4 cores (4nm)

Superior single thread **performance** with up to **5.1GHz**



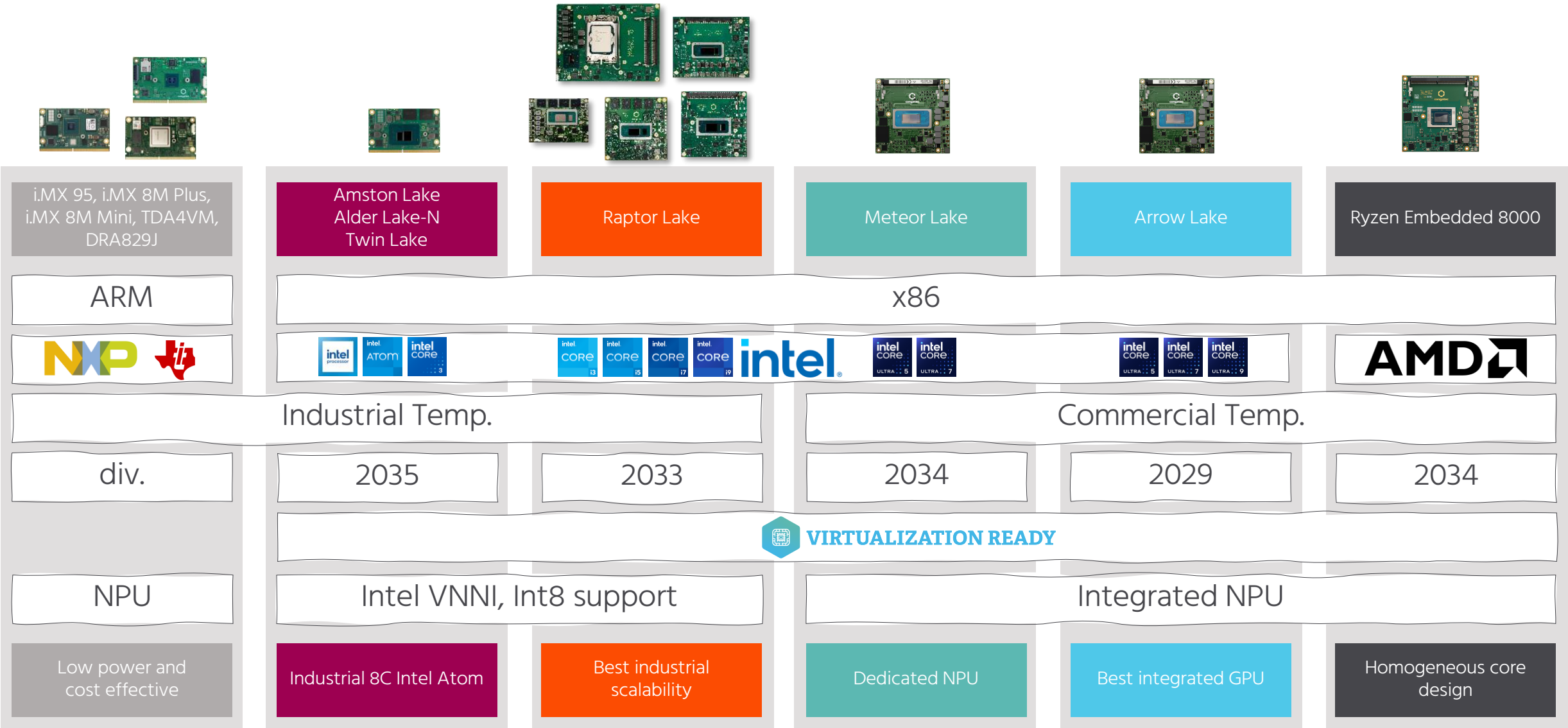
16 TOPS of dedicated AI performance with AMD **XDNA™ NPU**

Immersive graphics with **Radeon RDNA 3™** and up to 12 compute units (CUs)

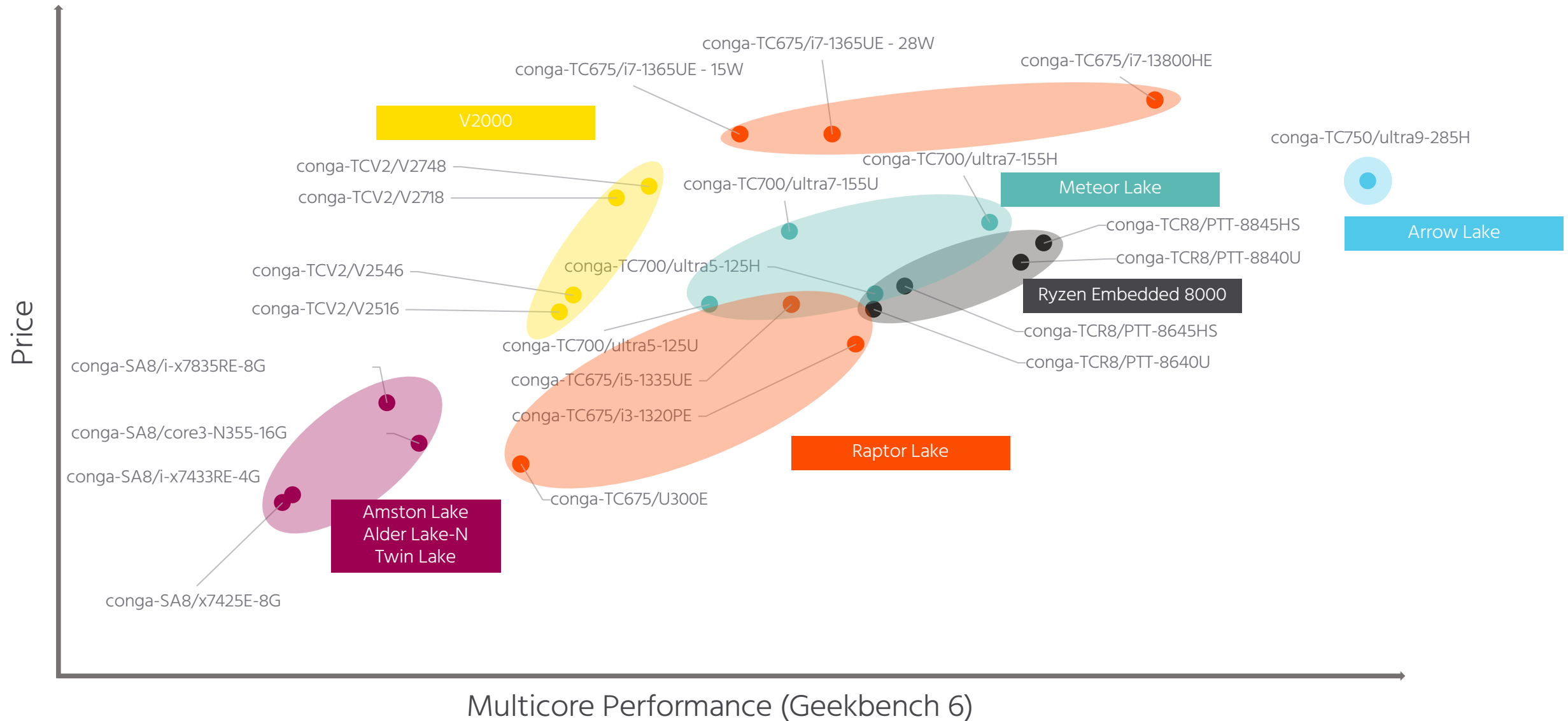
Easy design-in thanks to wide TDP range from **15W to 54W**

For **memory intensive applications** with up to **96GB** DDR5-5600 (ECC optional)

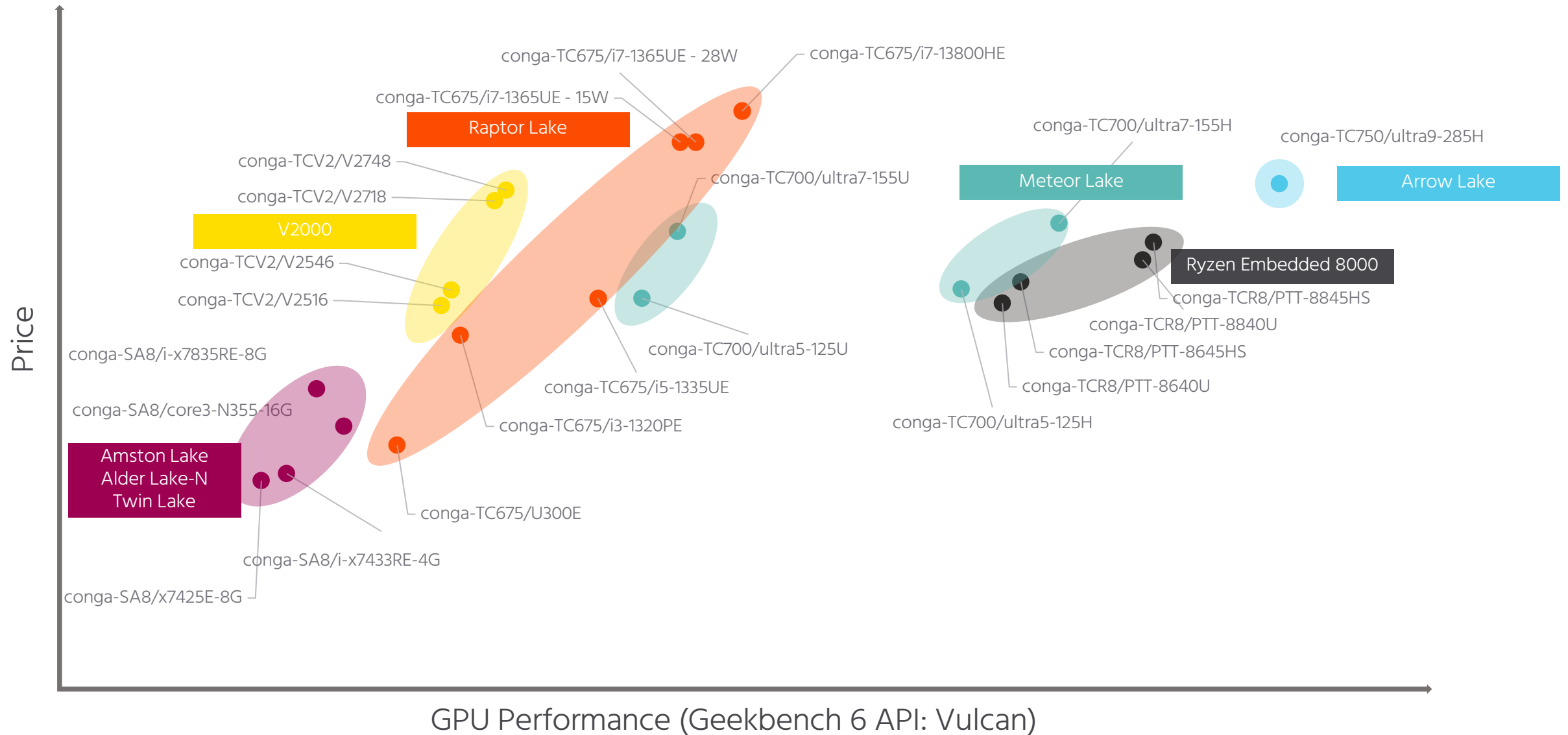
Broad Portfolio



Multicore Performance Landscape



GPU Performance Landscape

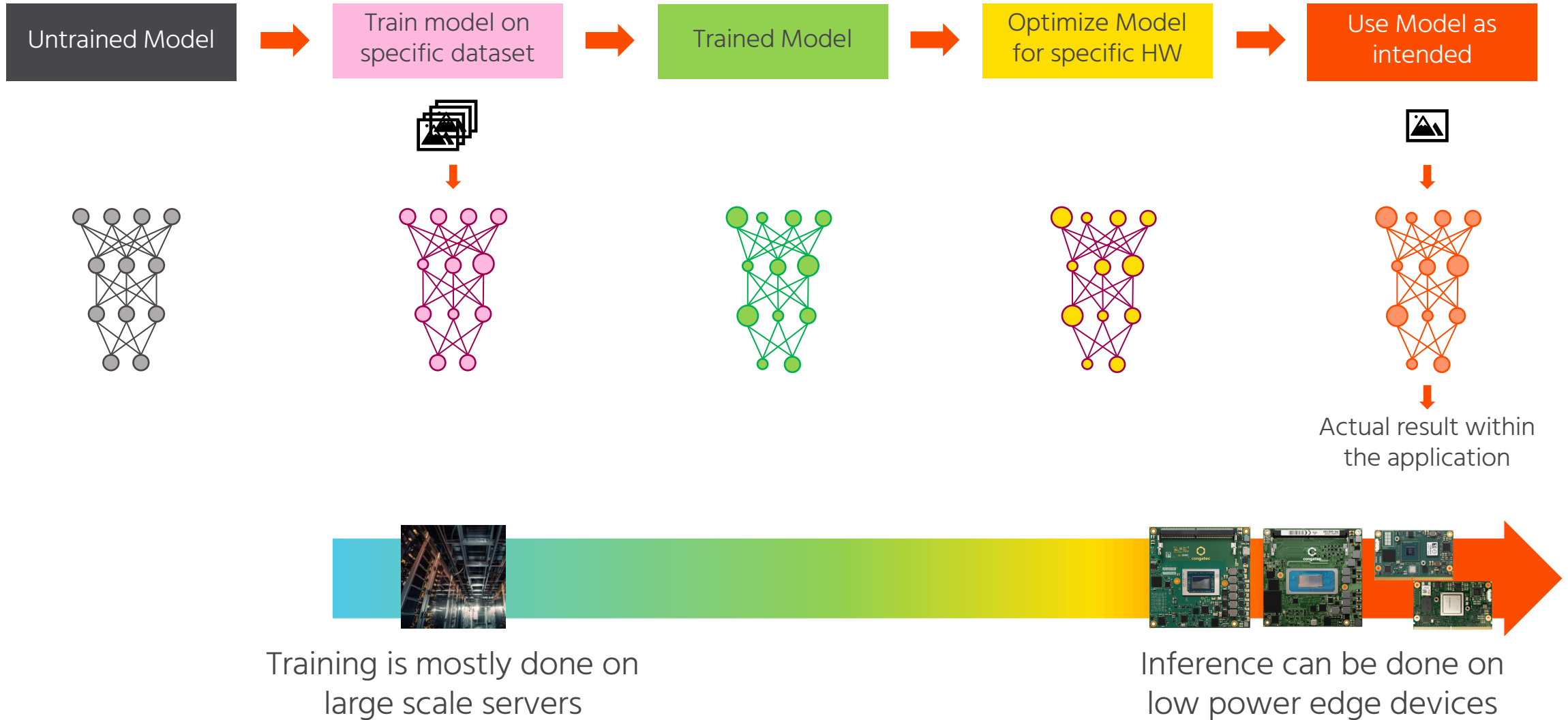




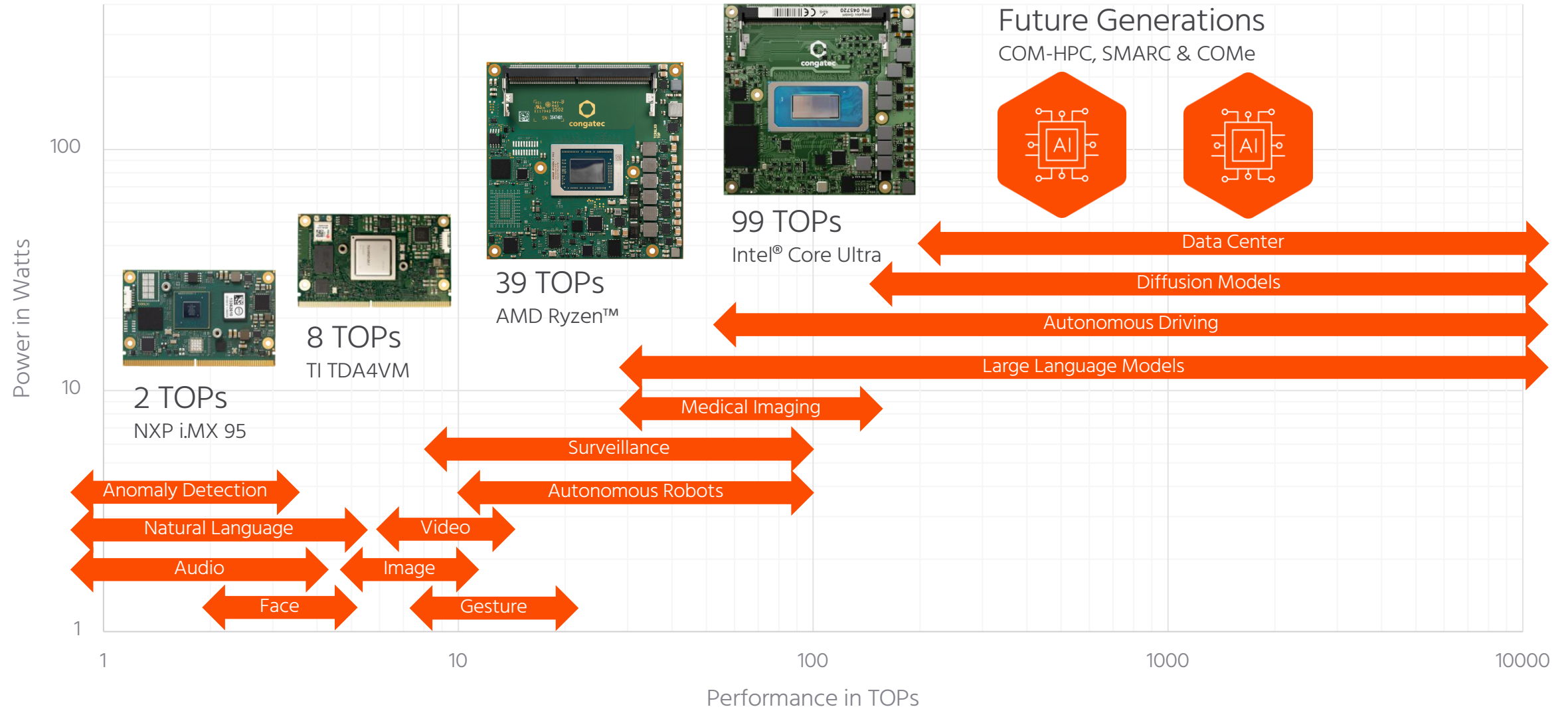
Artificial Intelligence



Training or Inference?

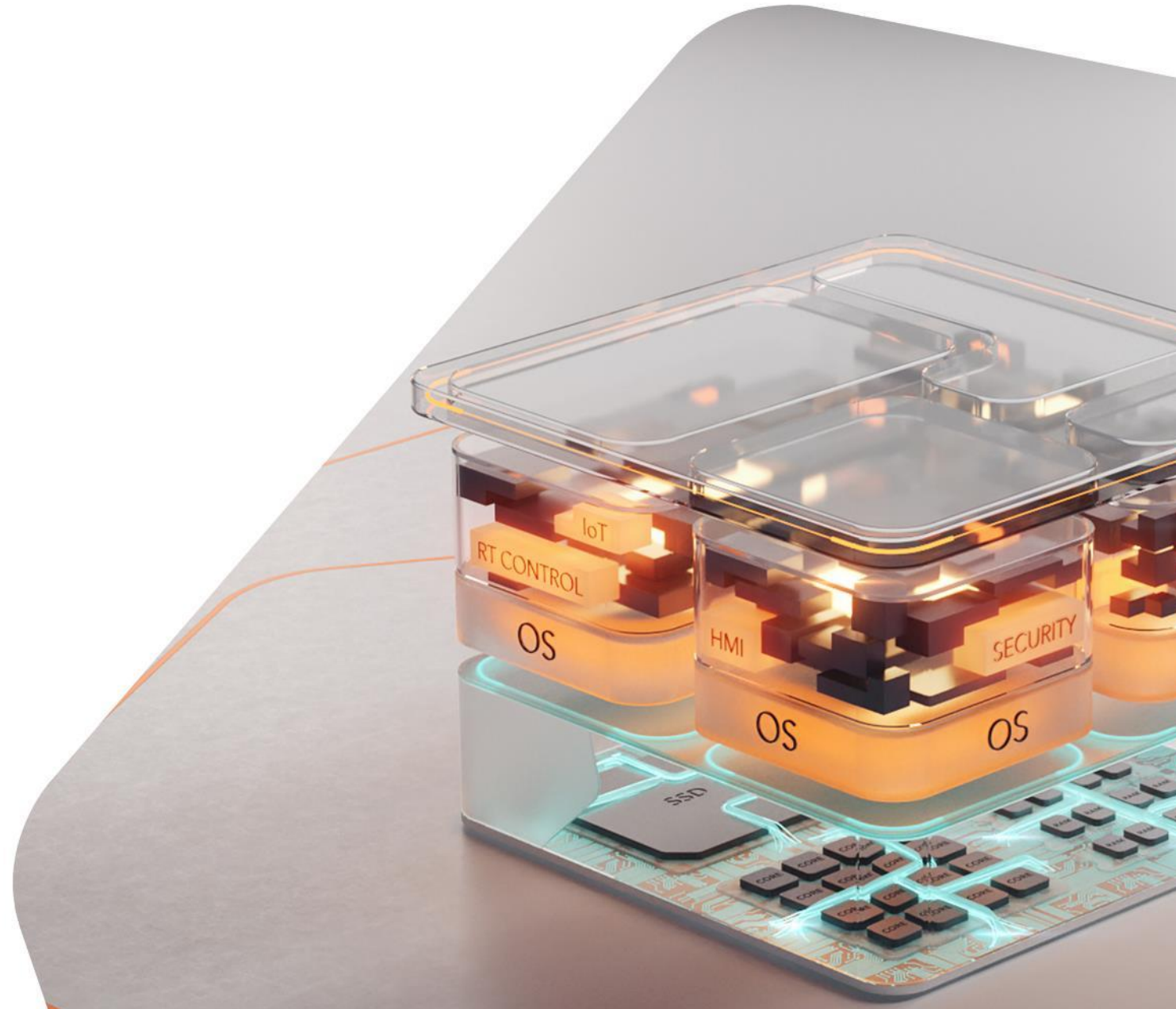


Training or Inferencing?



aReady. COM

Application-ready Computer-on-Modules from
congatec



- IoT building blocks by subscriptions models
- IoT building blocks by license
- ctrlX apps bundled with ctrlX OS

Software



- Image by customer license
- Image by congatec license

OS

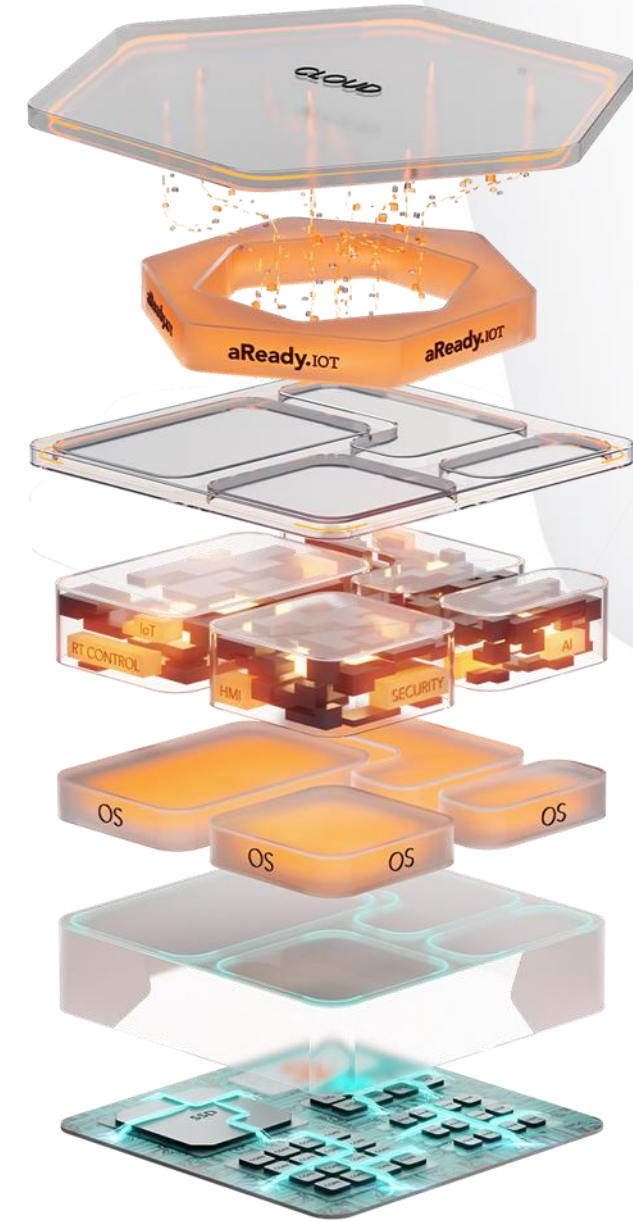


- Preinstalled/configured
- Trial License on Board
- Free demo OS images
- Enabling full license

Virtualization / Consolidation



Module



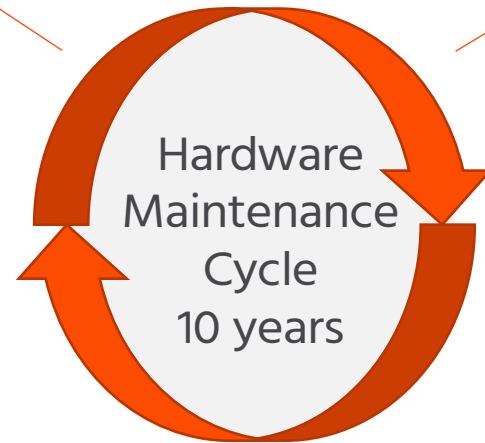
aReady. | Don't be just ready. Be application ready.

Ubuntu Certified Hardware

Canonical offers to certify hardware for the usage of Ubuntu software.

➔ Certified Devices are tested every 2 weeks against new Ubuntu updates

Update
Automatic/manual
push updates images



Patches
Bug fixes are
integrated into kernel

Regression Test
Run updated images on all
certified hardware



congatec modules will be Ubuntu certified as a standard offering. In addition to this we offer the certification of the customer system! (congatec module + customer carrier)



aReady. IOT



The past

- Standalone devices in the nowhere
- No stock information
- Slow response to failures
- Traveltime of technicians
- No health status



concept of building blocks

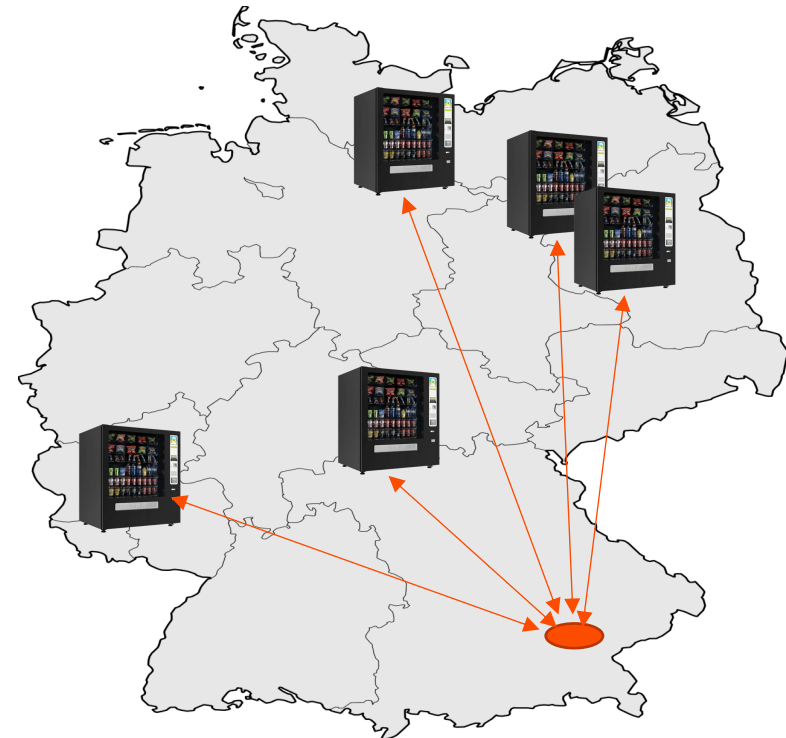
COM Manager



Application Manager



Fleet Manager



From centric to holistic: Main differentiator between the packages

- COM Manager is able to manage the COM itself.
- Application Manager offers the possibility to manage the whole application, including carrier and peripherals.
- The Fleet Manager is identical to the Application Manager and offers additional the grouping of devices and mass deployments of actions.

product offering

COM Manager



Application Manager



Fleet Manager



COM Hardware information



Remote control of COM



Dashboard



Software Maintenance



Remote Management of carrier and peripheral devices



Rule engine framework



Notification engine



Mass deployments of configurations and Updates



Cloud Connector

Allows to export all device data to an external Cloud, e.g. MS Azure IoT, AWS, Telekom Cloud



Description COM Manager



COM Manager

- Remote Control
- Hardware Information
- Dashboard
- Software Maintenance

Remote Management of COM

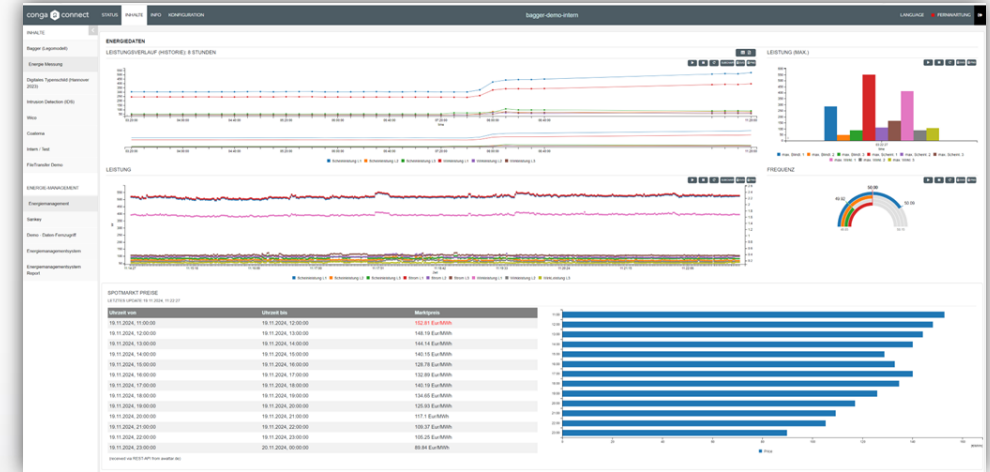
- Restart or shutdown: Remote start, stop or reboot.
- Software updates: Installing or updating operating systems and applications.
- Access to logs: Reading system logs for error analysis.

Software Maintenance

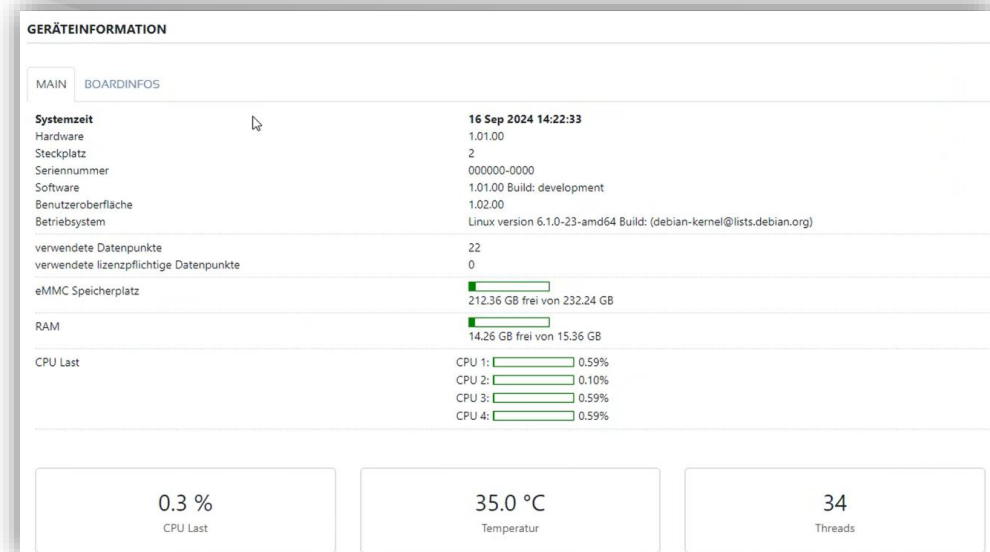
Remote Updates

- BIOS
- Firmware
- IoT Software Stack
- Hypervisor

HMI



Hardware Information



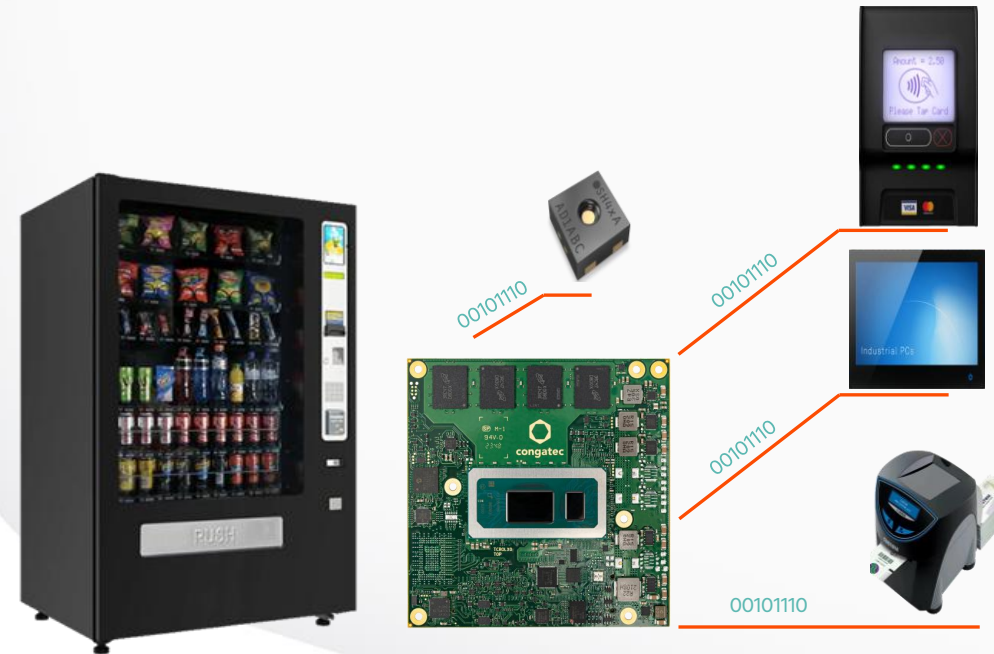
Description application manager

Notification Engine

- Notifications by email
- API to integrate 3rd party vendors and usage of messengers, SMS service and similar.

Industry standard communication protocols for connecting peripheral devices

- API to allow customer to add own hardware
- OPC UA Client and Server
- MQTT Broker and Client connection
- PLC Client: S7 / S5
- REST Client API
- Modbus Client
- Cloud IoT Service (Azure IoT, Telekom, AWS)
- Database (InfluxDB, SQLite), Connector Client (InfluxDB, MySQL)
- RFC 1006
- Notifications (SMTP Client)
- AAS Connector



Application Manager

- Remote Management of COM + Peripherals
- Industry standard communication protocols
- Rule Engine Framework
- Notification Engine
- Software Maintenance OTA

Description fleet manager

Definition of Device Groups

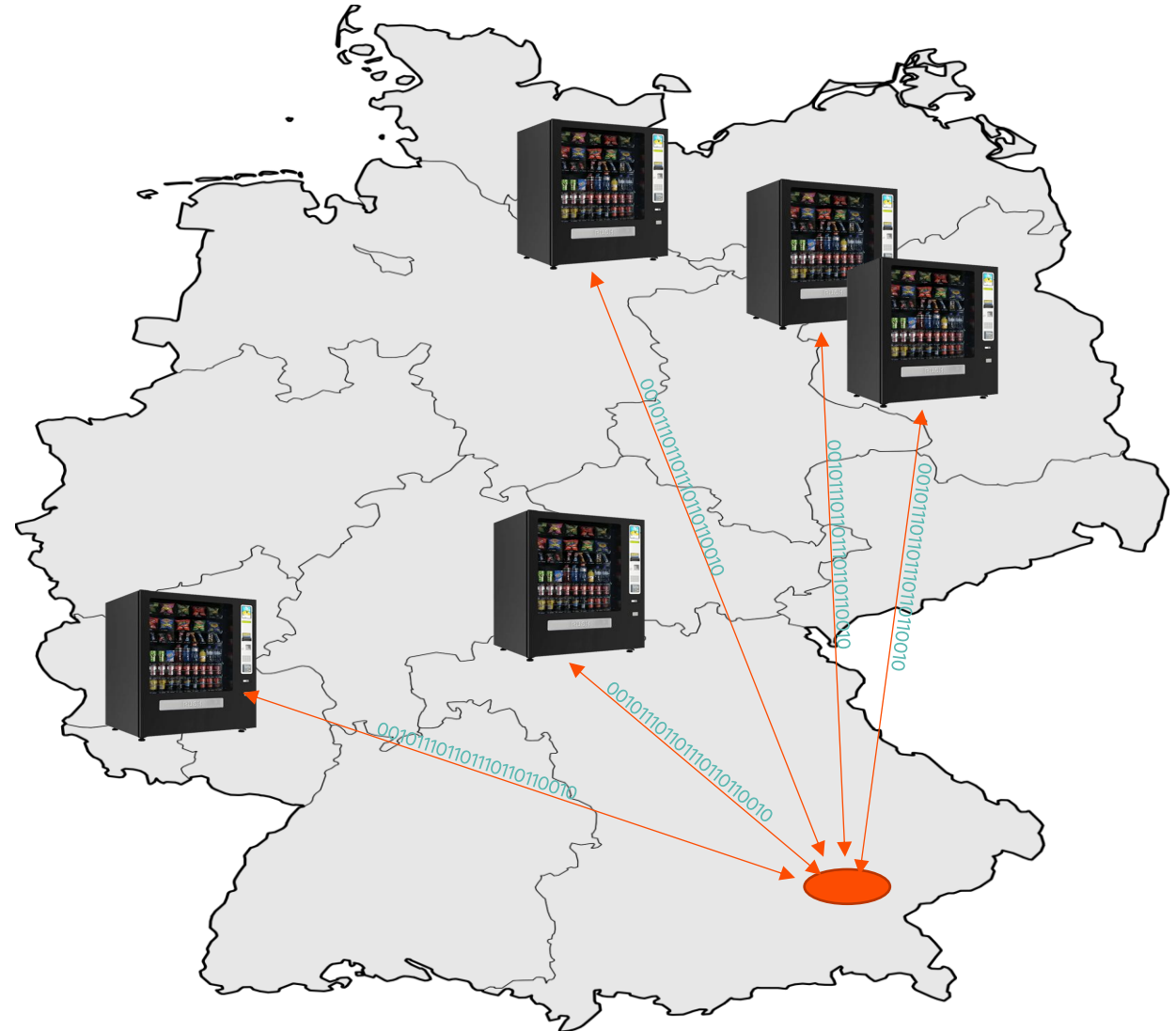
- Group Devices by different criteria
- Deploy actions to a group at devices at one time

Mass Deployments

Remote Updates

- Configuration files
- BIOS
- Firmware
- IoT Software Stack
- Hypervisor

Fleet Manager



description cloud connector

Allows to export all device data to an external Cloud, e.g. MS Azure IoT, AWS, Telekom Cloud

- Data Analysis and Visualization
- Alerts and Notifications
- Optimization and Control
- Data Integration
- Long-Term Storage
- Machine Learning and AI
- Security and Access Management



The past

- Standalone devices in the nowhere
- No stock information
- Slow response to failures



Today

- Connected devices
- Available health status and business figures
- Fast maintenance response



conga connect				
STATUS				
EREIGNISPROTOKOLL				
Zeit	Thema	Schwerer	Auslöser	Meldung
Montag, 25.11.2024				
25.11.2024 10:56:09	00012000	OK	DatensatzHuiDCConnector (HuiDCR_V2_10.8_1.0)	Initialisation already started (start active)
25.11.2024 10:56:09	00012000	OK	DatensatzHuiDCConnector (HuiDCR_V2_10.8_1.0)	restart Initiale Connector (sewerlogCommand), state OFFLINE
25.11.2024 10:56:09	01013126	OK	DatensatzHuiDCConnector (HuiDCR_V2_10.8_1.0)	initialisation already started (start active)
25.11.2024 10:56:09	01013126	OK	DatensatzHuiDCConnector (HuiDCR_V2_10.8_1.0)	restart Initiale Connector (sewerlogCommand), state OFFLINE
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aReady.
VT



Virtualization Technology

- Hypervisor-on-Modules
- Easier access to VT
- Demonstrate software competence
- RTS Hypervisor
- Secure Bootloader
- **Coming Soon**
 - Secure Hypervisor (IEC 62443 Certified)



OS Support

— Compatible:



— Featured:



— Next:

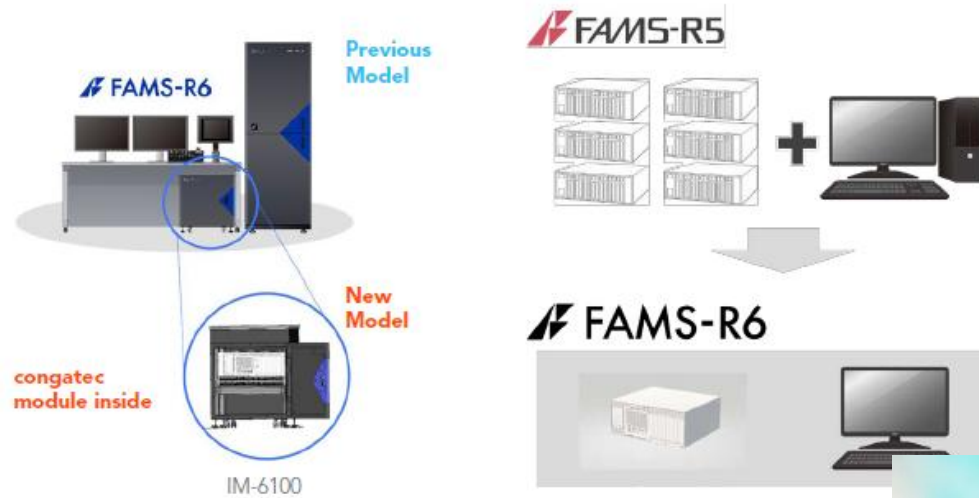


<https://www.real-time-systems.com/products/os-compatibility/>

Customer Reference: Ono Sokki



Real-Time Hypervisor Success Case | IM-6100 (FAMS Unit)



System consolidation enabled Ono Sokki to reduce the number of PC systems necessary for any test installation from as many as seven to only one.

Cutting complexity with a single module design

Ono Sokki reduces hardware requirements for its automotive measurement systems from seven to one with congatec's computer-on-module and hypervisor

CASE STUDY

Cutting complexity with a single module design

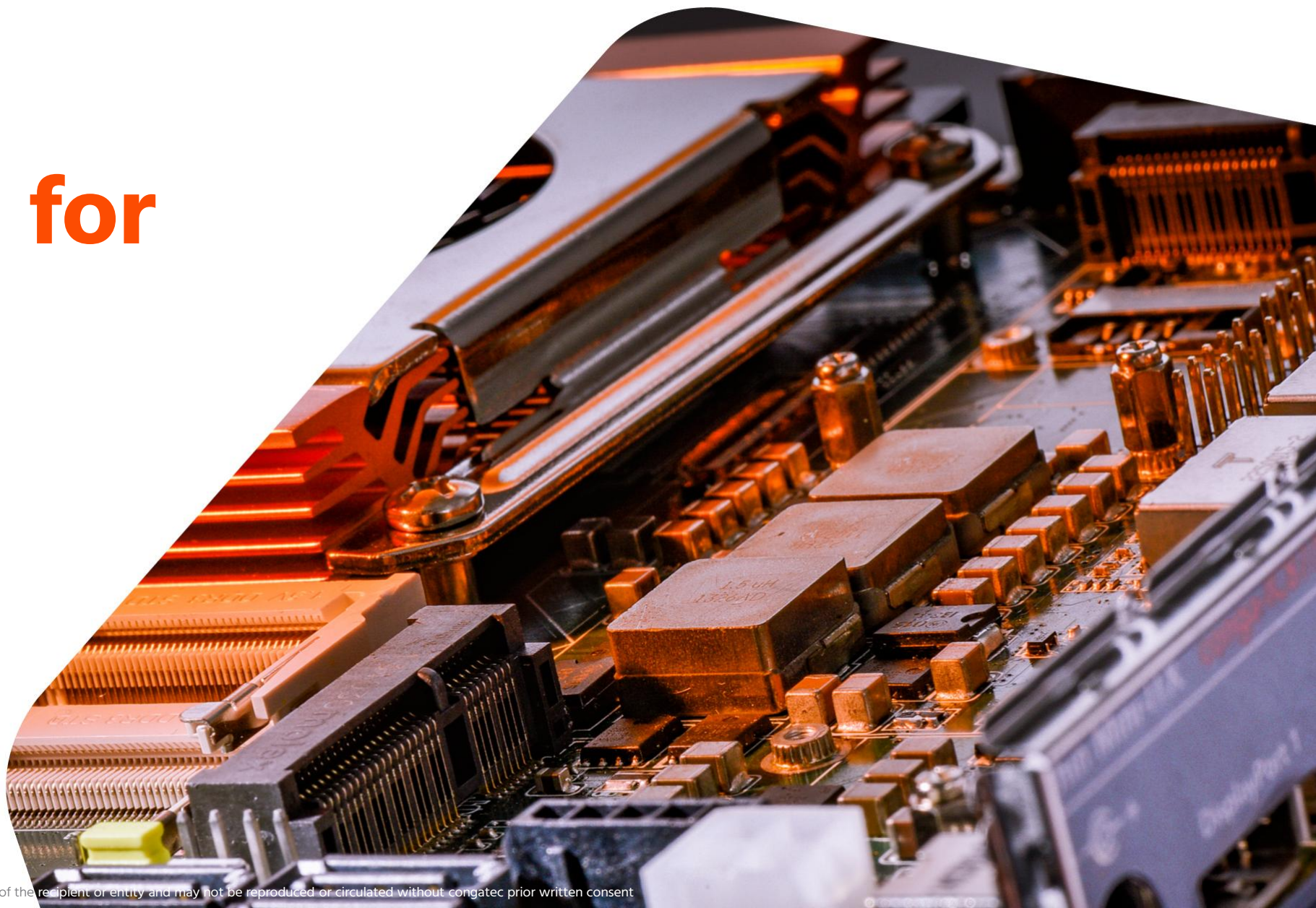
See system consolidation in action! Ono Sokki reduced hardware requirements for its test and measurement solution by going from seven systems down to just one with congatec's Computer-on-Modules and real-time hypervisor.

[Download Now](#)



Thank you for your time.

Questions?



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